

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2642086

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHIN-CHUAN CHANG</td> <td>12/04/2013</td> </tr> <tr> <td>TSEI-CHUNG FU</td> <td>12/04/2013</td> </tr> <tr> <td>JING-CHENG LIN</td> <td>12/04/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHIN-CHUAN CHANG	12/04/2013	TSEI-CHUNG FU	12/04/2013	JING-CHENG LIN	12/04/2013		
Name	Execution Date										
CHIN-CHUAN CHANG	12/04/2013										
TSEI-CHUNG FU	12/04/2013										
JING-CHENG LIN	12/04/2013										
RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. (TSMC)</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN RD. 6, SCIENCE-BASED INDUSTRIAL PARK</td> </tr> <tr> <td>City:</td> <td>HSIN-CHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. (TSMC)	Street Address:	NO. 8, LI-HSIN RD. 6, SCIENCE-BASED INDUSTRIAL PARK	City:	HSIN-CHU	State/Country:	TAIWAN	Postal Code:	300-77
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. (TSMC)										
Street Address:	NO. 8, LI-HSIN RD. 6, SCIENCE-BASED INDUSTRIAL PARK										
City:	HSIN-CHU										
State/Country:	TAIWAN										
Postal Code:	300-77										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14100987</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14100987						
Property Type	Number										
Application Number:	14100987										
CORRESPONDENCE DATA											
<p>Fax Number: (972)732-9218</p> <p>Phone: 972-732-1001</p> <p>Email: docketing@slater-matsil.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: SLATER & MATSIL, L.L.P.</p> <p>Address Line 1: 17950 PRESTON ROAD, SUITE 1000</p> <p>Address Line 4: DALLAS, TEXAS 75252</p>											
ATTORNEY DOCKET NUMBER:	TSM13-0961										
NAME OF SUBMITTER:	CINDY C. STOUTEN										
Signature:	/Cindy C. Stouten/										
Date:	12/09/2013										
<p>Total Attachments: 1</p> <p>source=TSM13-0961-Assignment#page1.tif</p>											

CH \$40.00 14100987

PATENT

ATTORNEY DOCKET NO.
TSM13-0961

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu 300-77, Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Protective Layer for Contact Pads in Fan-out Interconnect Structure and Method of Forming Same		
SIGNATURE OF INVENTOR AND NAME	<i>Chin-Chuan Chang</i> Chin-Chuan Chang	<i>T. C. Fu</i> Tsei-Chung Fu	<i>Ji-Cheng Lin</i> Jing-Cheng Lin
DATE	2013.12.4	2013, 12, 04	2013.12.4
RESIDENCE	Zhudong Township, Taiwan, R.O.C.	Toufen Township, Taiwan, R.O.C.	Chu Tung Zhen, Taiwan, R.O.C.